

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

RCLAMP3324P

Product specification

FEATURES

- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (Cj=0.25pF typ. IO-IO)
- IEC 61000-4-2
±20kV (contact
discharge) ±20kV
(air discharge)
- IEC 61000-4-4 (EFT) 40A (5/50ns)

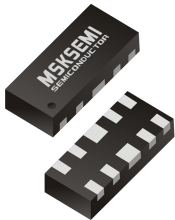
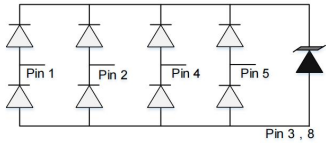
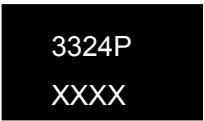
MACHANICAL DATA

- Tiny DFN-10(2.5mmx1.0mm) package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

APPLICATIONS

- USB2.0, USB3.0 interface
- HDMI1.3,HDMI1.4 and HDMI2.0
- industrial equipment
- Digital Visual Interface
- Notebooks

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		
<p>DFN-10</p>		

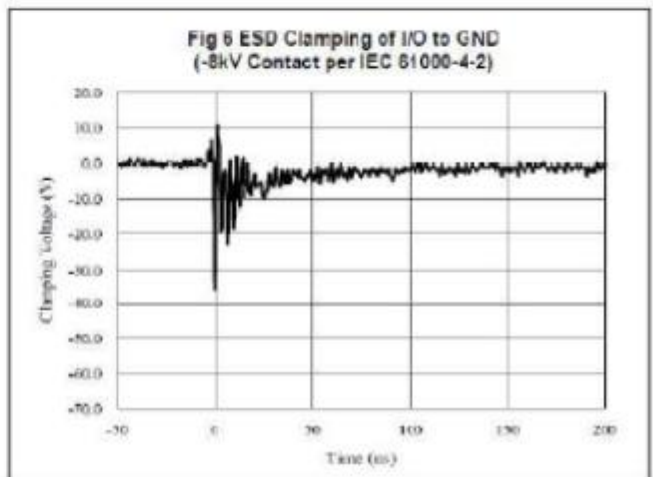
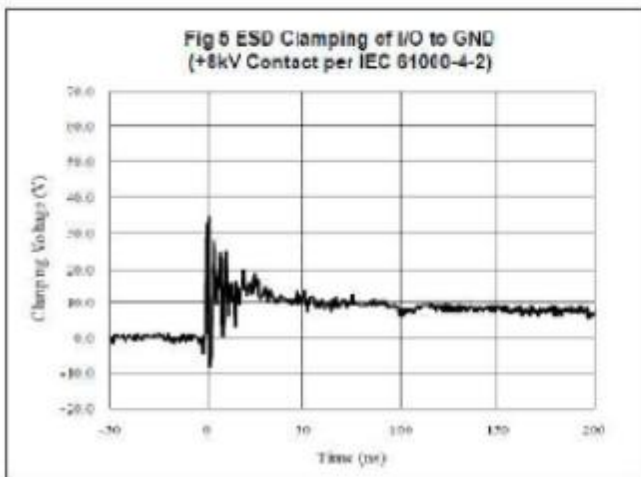
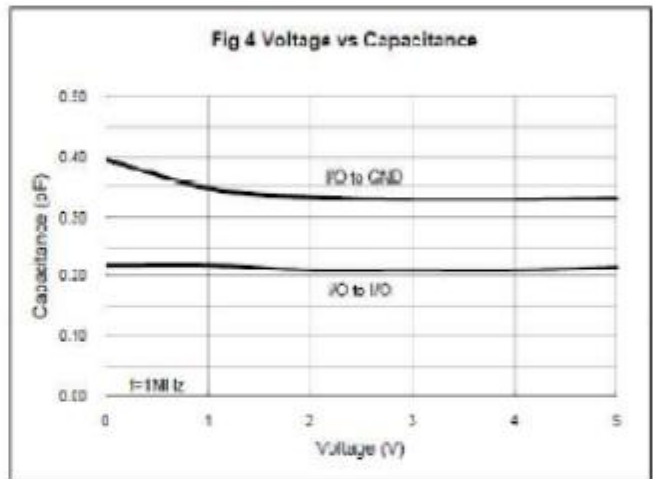
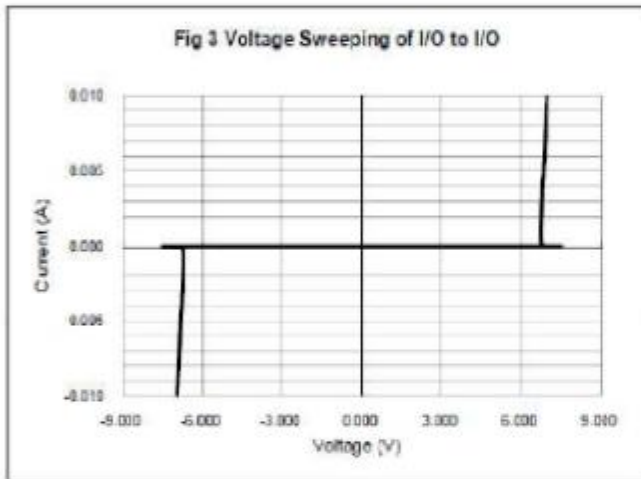
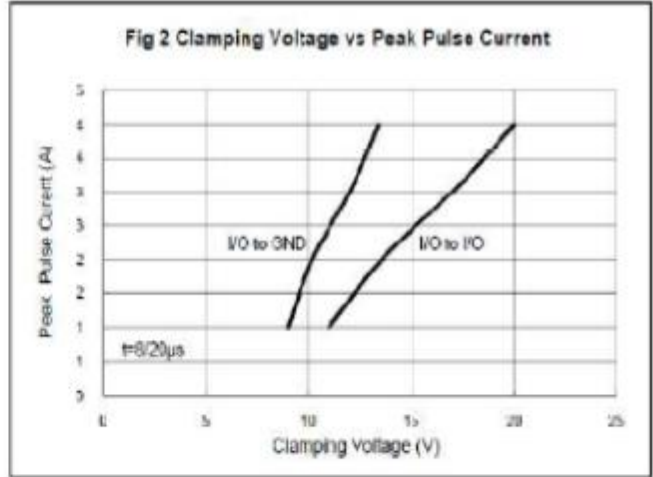
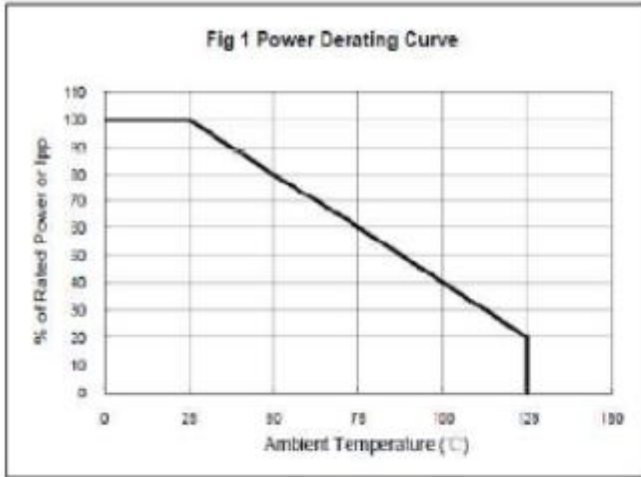
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
VESD	ESD per IEC 61000-4-2 (Contact)	±20	kV
	ESD per IEC 61000-4-2 (Air)	±20	
PPP	Peak Pulse Power (8/20µs)	60	W
TOPT	Operating Temperature	-55~125	°C
TSTG	Storage Temperature	-55~150	°C

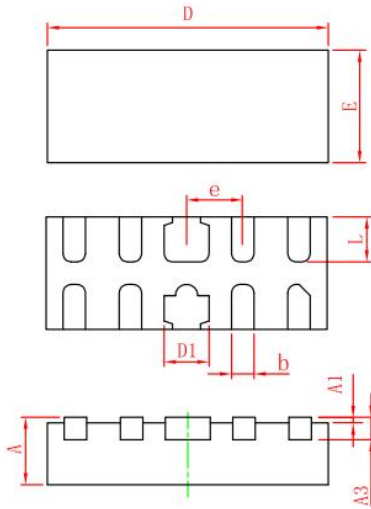
ELECTRICAL CHARACTERISTICS (Tamb=25°C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
	Reverse Working Voltage				3.3	V
VBR	Reverse Breakdown Voltage	IT = 1mA	4.2			V
IR	Reverse Leakage Current	V _{RWM} =3.3V, T=25C			100	nA
VC	Clamping Voltage	I _{PP} = 4A, t _p = 8/20µs			15	V
CJ	Junction Capacitance	VR = 0V, f = 1MHz		0.25	0.4	pF
		IO to IO				
		VR = 0V, f = 1MHz		0.4	0.6	pF
		IO to Gnd				

ELECTRICAL CHARACTERISTICS CURVE



PACKAGE MECHANICAL DATA



Symbol	Dimensions in millimeters		
	Min	Nom	Max
A	0.45	0.50	0.55
A1	-	0.02	0.05
A3	0.10	0.15	0.20
D	2.45	2.50	2.55
E	0.95	1.00	1.05
D1	0.35	0.40	0.45
b	0.15	0.20	0.25
e	0.50BSC		
L	0.35	0.40	0.45

REEL SPECIFICATION

P/N	PKG	QTY
RCLAMP3324P	DFN-10	3000

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